

IN THE CLAIMS:

1. (Once Amended) A package for containing semiconductor element comprising:
a [package] housing having a recess portion for containing a semiconductor element;
and
a pair of positioning holes and a pair of attaching holes respectively provided at [a pair of] opposed side portions of said [recess portion at a surface of said package] housing,
wherein a line [connecting] between said pair of positioning holes and a line
[connecting] between said pair of attaching holes [are intersected] intersect with each other
substantially at a center of said package and further wherein the line between the positioning
holes is skewed with respect to each of the side walls of the housing and the line between the
attaching holes is skewed with respect to each of the side walls.

3. (Once Amended) A semiconductor device comprising:
a semiconductor element;
a [package] housing having a recess portion for containing said semiconductor
element; and
a pair of positioning holes and a pair of attaching holes respectively provided at [a pair of] opposed side portions of said [recess portion at a surface of said package] housing;
wherein a line [connecting] between the pair of positioning holes and a line
[connecting] between said pair of attaching holes [are intersected] intersect with each other
substantially at a center of said package and further wherein the line between the positioning
holes is skewed with respect to each of the side walls of the housing and the line between the
attaching holes is skewed with respect to each of the side walls.

5. (Once Amended) A semiconductor device comprising:

- a semiconductor element;
- a [package] housing having a recess portion for containing said semiconductor element;
- a pair of attaching holes provided at [a pair of] opposed side portions of said [recess portion] housing at a surface of said package; and
- a transparent member for sealing said semiconductor element in said recess portion;

wherein said surface of said [package] housing is made to be higher than a top surface of said transparent member.